

What is claimed is:

1. A hotmelt adhesive composition for the coating and/or lamination of sheetlike structures, wherein upper
5 dot and lower dot are based on an amine-terminated crosslinkable copolyamide and the lower dot further comprises a crosslinker and an acrylic and/or PU dispersion.
- 10 2. A hotmelt adhesive composition as claimed in claim 1, wherein the copolyamide is an amine-regulated copolyamide powder having a melting range of 90 to 150°C and a solution viscosity η_{rel} in the range from 1.2 to 1.7.
- 15 3. A hotmelt adhesive composition as claimed in either of the preceding claims, wherein the upper dot comprises an amine-regulated copolyamide.
- 20 4. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the lower dot comprises an amine-regulated copolyamide.
- 25 5. A hotmelt adhesive composition as claimed in claim 1, comprising an acrylate dispersion and/or polyurethane dispersion.
- 30 6. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the crosslinking component comes from the group of the isocyanates and has more than two reactive groups per molecule.
- 35 7. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the isocyanate has a melting range of from 100 to 130°C.
8. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein an epoxide having a

melting range of from 90 to 130°C, a molecular weight range from 2000 to 6000 and more than two epoxide groups per molecule is employed as crosslinking component.

- 5 9. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein a pulverulent free or blocked isocyanate is employed as crosslinking component.
- 10 10. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the amine-regulated copolyamides in the upper dot and lower dot have different melting temperatures or viscosities.
- 15 11. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the crosslinking component is an epichlorohydrin.
- 20 12. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the reactive component is a di- and/or triacrylate.
- 25 13. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the reactive amine-regulated copolyamide is employed as base dot for the double dot technology, as a strikethrough barrier.
- 30 14. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the base dot consists of a passivated isocyanate and an amine-regulated copolyamide and is applied in halftone formation as a paste.
- 35 15. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the crosslinking reaction is accelerated by catalysts.
16. A hotmelt adhesive composition as claimed in any of the preceding claims, wherein the copolyamides are based

on lactames (LL, CL), dimer fatty acids and corresponding dicarboxylic acids and diamines having chain lengths of C2 o C15 and piperazine.

5 17. The use of a hotmelt adhesive composition as claimed in any of the preceding claims for the coating and/or lamination of sheetlike structures.

10 18. An interlining material for clothing, which has been provided with a hotmelt adhesive composition as claimed in any of the preceding claims.